

IMBA-H61A

Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: <u>Temperature at one component was estimated to be in marginal temperature point in comparison with component datasheet.</u>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	1
Defect Unsolved	0	0	0	1

Issue date	Approval	Test Engineer
2013 / 02 / 19	Tom Lin	Matthew Chi

Sample Configuration & Quantity Under Test

- **Model name** : IMBA-H61A A1.00
- **CPU** : Intel Core i7-2600 3.40GHz
- **Chipset** : Intel H61
- **Memory** : Transcend 8G DDR3 1333 HYKO K4B4G0846B
- **SATA HDD** : TOSHIBA MK1665GSX 2.5" 160G
- **BIOS** : 0104(12/28/2012)
- **Test Software** : Windows 7 / Run PassMark Burn In Test 7.0
- **Power** : AT Power CWT DSA400P-C
- **CPU Fan:**



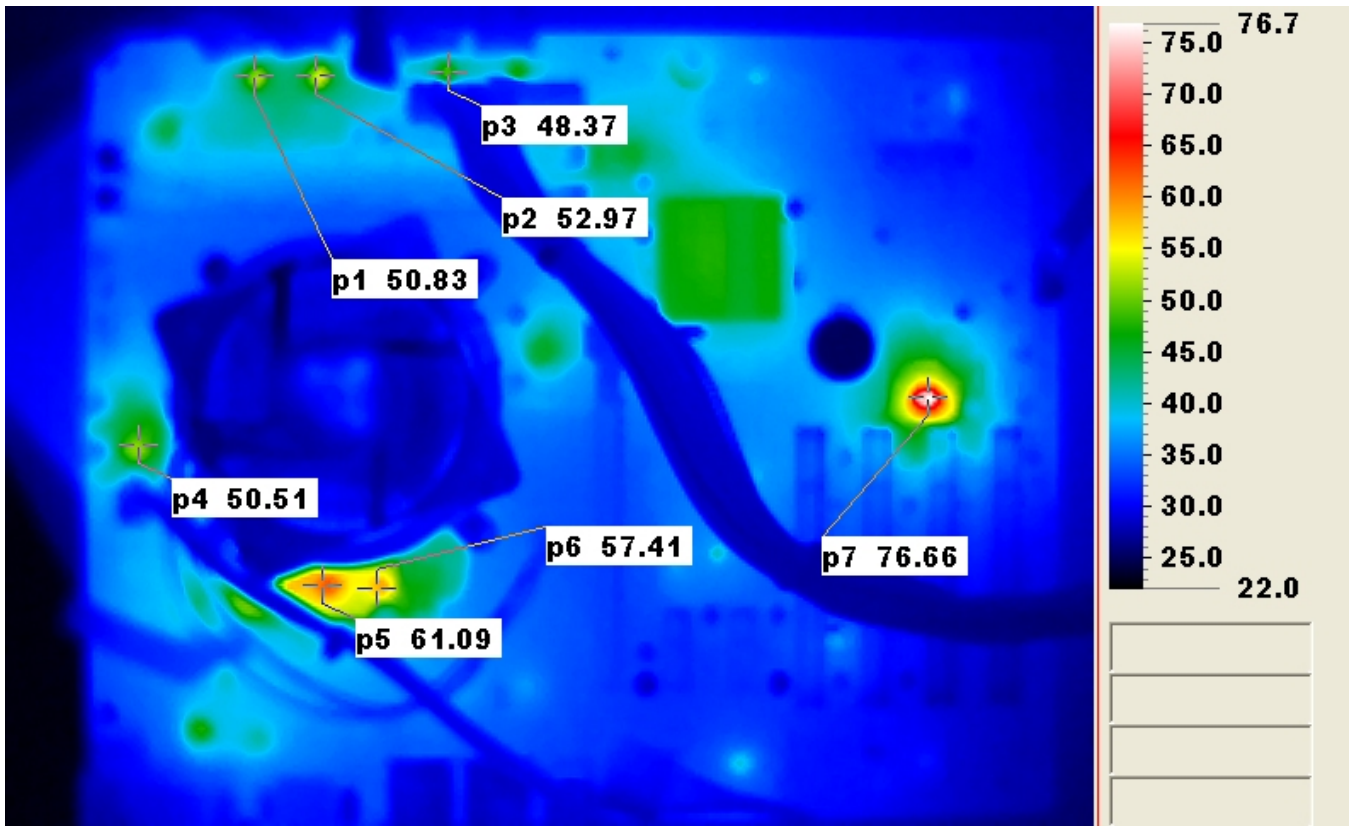
Thermal Image Analysis

1. Test Date: 2013-02-19
2. Test Product: IMBA-H61A
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
 - 4.1. 40 Channel Thermal Recorder:
 - 4.1.1 YOKOGAWA Inc,
 - 4.2.2 Model: DA100-13-1D
Date of Calibration: 2013/10/07
Serial Number: 12A323190
 - 4.2. IR Scanner: Infrared Camera
 - 4.2.1 NIPPON AVIONICS CO., LTD.
 - 4.2.2 Model: NEC-G100D
Date of Calibration: 2014/01/ 09
Serial Number: 1051444
5. Test Condition:

Component Side-1 (Test by DA-100): 25.0°C With CPU Fan
6. Take Picture Time:

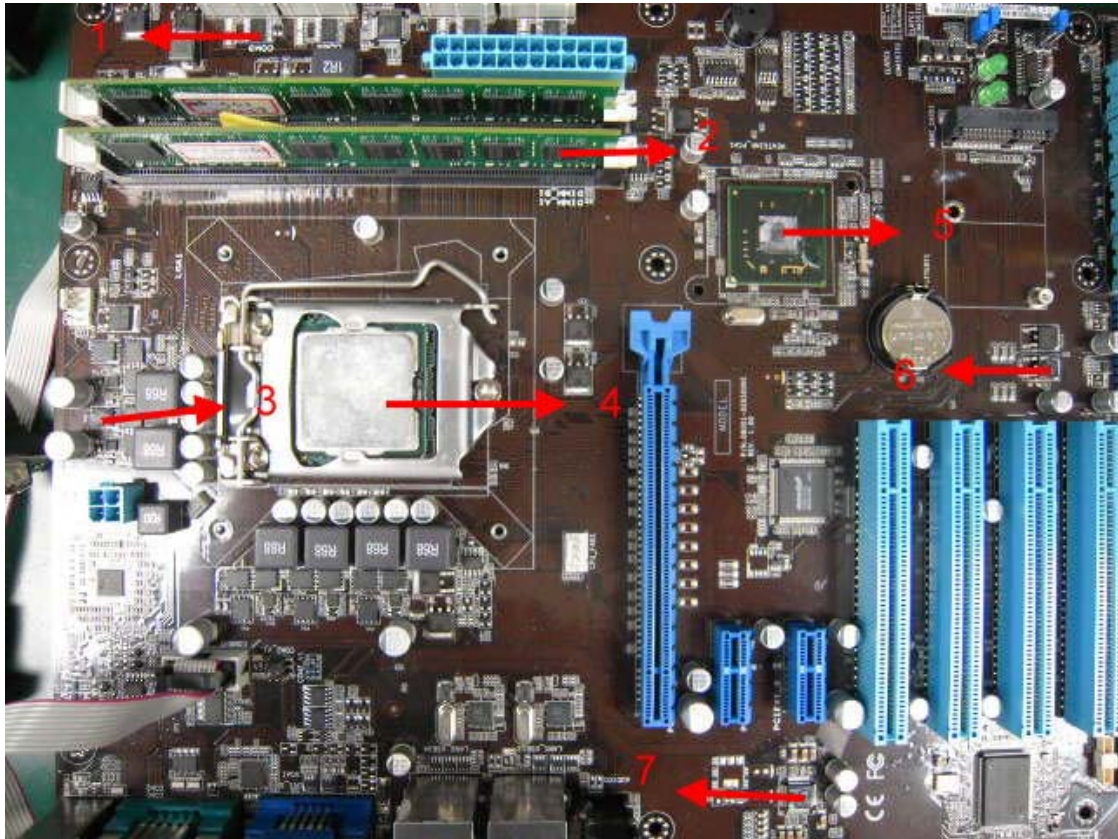
After power on 2 hours

Temperature Profile Test:
Component Side:



Terminal Recorder:

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25°C	60°C	
1	Ou11	MULTIPLE RS-232 DRIVERS AND RECEIVERS AZ75232	100	48.3	83.3	
2	Memory	Transcend 8G DDR3 1333 HYKO K4B4G0846B	85	38.4	73.4	
3	PQ7	Power MOSFET NTMFS4955N	125	28.5	63.5	
4	CPU	Intel Core i7-2600 3.40GHz	72.6	42.2	77.2	
5	Su1	(TF)IC.SMD.Platform Controller Hub.INTEL.BD82H61.SLJ4B	125	48.9	83.9	
6	Oq42	Power MOSFET AP3310GH/J	150	45.7	80.7	
7	Au1	C.S ALC887-VD2-CG LQFP-48//REALTEK	100.5	38.3	73.3	

Note(*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
- **Margin** : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.